

# Microcontrollers & Digital ICs Group Presentation



**Capital  
Markets  
Day 2020**

# Forward looking information

*Some of the statements contained in this release that are not historical facts are statements of future expectations and other forward-looking statements (within the meaning of Section 27A of the Securities Act of 1933 or Section 21E of the Securities Exchange Act of 1934, each as amended) that are based on management's current views and assumptions, and are conditioned upon and also involve known and unknown risks and uncertainties that could cause actual results, performance, or events to differ materially from those anticipated by such statements, due to, among other factors:*

- changes in global trade policies, including the adoption and expansion of tariffs and trade barriers, that could affect the macro-economic environment and adversely impact the demand for our products;*
- uncertain macro-economic and industry trends, which may impact end-market demand for our products;*
- customer demand that differs from projections;*
- the ability to design, manufacture and sell innovative products in a rapidly changing technological environment;*
- changes in economic, social, public health, labor, political, or infrastructure conditions in the locations where we, our customers, or our suppliers operate, including as a result of macroeconomic or regional events, military conflicts, social unrest, labor actions, or terrorist activities;*
- unanticipated events or circumstances, which may impact our ability to execute our plans and/or meet the objectives of our R&D and manufacturing programs, which benefit from public funding;*
- the Brexit vote and the impact of the withdrawal of the U.K. may adversely affect business activity, political stability and economic conditions in the U.K., the Eurozone, the EU and elsewhere. The U.K. withdrawal from the EU took place on January 31, 2020 and the UK majority government is expected to complete Brexit even if no formal withdrawal agreement is in place with the EU by the end of the transition period running until December 31, 2020. The specific terms of the U.K. withdrawal from the EU are still uncertain and while we do not have material operations in the U.K. and have not experienced any material impact from Brexit on our underlying business to date, we cannot predict its future implications;*
- financial difficulties with any of our major distributors or significant curtailment of purchases by key customers;*
- the loading, product mix, and manufacturing performance of our production facilities and/or our required volume to fulfill capacity reserved with suppliers or third party manufacturing providers;*
- availability and costs of equipment, raw materials, utilities, third-party manufacturing services and technology, or other supplies required by our operations;*
- the functionalities and performance of our IT systems, which are subject to cybersecurity threats and which support our critical operational activities including manufacturing, finance and sales, and any breaches of our IT systems or those of our customers or suppliers;*
- theft, loss, or misuse of personal data about our employees, customers, or other third parties, and breaches of global and local privacy legislation, including the EU's General Data Protection Regulation ("GDPR");*
- the impact of intellectual property ("IP") claims by our competitors or other third parties, and our ability to obtain required licenses on reasonable terms and conditions;*
- changes in our overall tax position as a result of changes in tax rules, new or revised legislation, the outcome of tax audits or changes in international tax treaties which may impact our results of operations as well as our ability to accurately estimate tax credits, benefits, deductions and provisions and to realize deferred tax assets;*
- variations in the foreign exchange markets and, more particularly, the U.S. dollar exchange rate as compared to the Euro and the other major currencies we use for our operations;*
- the outcome of ongoing litigation as well as the impact of any new litigation to which we may become a defendant;*
- product liability or warranty claims, claims based on epidemic or delivery failure, or other claims relating to our products, or recalls by our customers for products containing our parts;*
- natural events such as severe weather, earthquakes, tsunamis, volcano eruptions or other acts of nature, the effects of climate change, health risks and epidemics such as the novel coronavirus COVID-19 in locations where we, our customers or our suppliers operate;*
- industry changes resulting from vertical and horizontal consolidation among our suppliers, competitors, and customers; and*
- the ability to successfully ramp up new programs that could be impacted by factors beyond our control, including the availability of critical third party components and performance of subcontractors in line with our expectations.*

*Such forward-looking statements are subject to various risks and uncertainties, which may cause actual results and performance of our business to differ materially and adversely from the forward-looking statements. Certain forward-looking statements can be identified by the use of forward looking terminology, such as "believes," "expects," "may," "are expected to," "should," "would be," "seeks" or "anticipates" or similar expressions or the negative thereof or other variations thereof or comparable terminology, or by discussions of strategy, plans or intentions.*

*Some of these risk factors are set forth and are discussed in more detail in "Item 3. Key Information — Risk Factors" included in our Annual Report on Form 20-F for the year ended December 31, 2019, as filed with the SEC on February 26, 2020. Should one or more of these risks or uncertainties materialize, or should underlying assumptions prove incorrect, actual results may vary materially from those described in this release as anticipated, believed, or expected. We do not intend, and do not assume any obligation, to update any industry information or forward-looking statements set forth in this release to reflect subsequent events or circumstances.*

# Introduction

**Jean-Marc Chery**

President & CEO



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Markets  
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# Our value proposition

## For our shareholders



Return value in line with our sustainable, profitable growth objective

Sustainable and profitable growth

## For our customers



Provide differentiating enablers

Independent, reliable & secure supply chain

## For other stakeholders



Committed to sustainability

Our values: Integrity – People – Excellence

# Our strategy stems from key long-term enablers

## Smart Mobility



**ST** provides innovative solutions to help our customers make driving **safer, greener and more connected** for everyone

## Power & Energy



**ST** technology and solutions enable customers to increase **energy efficiency** everywhere and support the use of renewable energy sources

## Internet of Things & 5G



**ST** provides **sensors, embedded processing solutions, connectivity, security and power management**, as well as **tools and ecosystems** to make development fast and easy for our customers

# We address four end markets

## Automotive



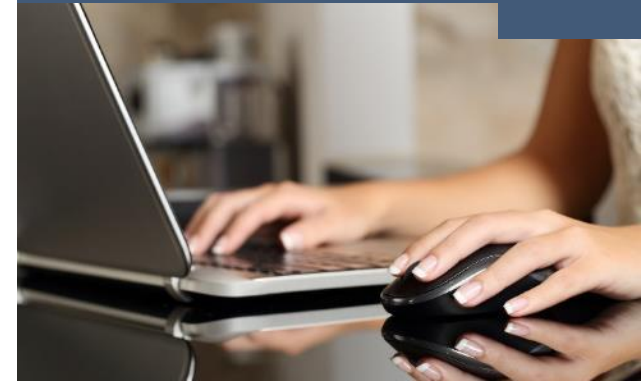
## Industrial



## Personal electronics



## Communications equipment, computers & peripherals

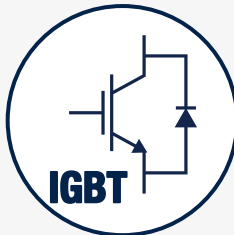
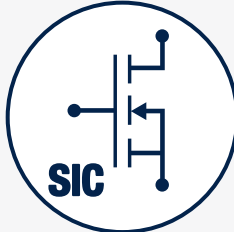


# ST product portfolio enabling strategic trends

Dedicated Automotive ICs



Discrete & Power Transistors



Analog, Industrial & Power Conversion ICs



GP, Connected MCU, MPU  
Secure MCU, EEPROM



MEMS & Optical sensing solutions



ASICs based on ST proprietary technologies



Smart Mobility

Power & Energy

Internet of Things & 5G

# Our strategic objectives

## Automotive



Lead in **car electrification**



Lead in **car digitalization**

## Industrial



Lead in **embedded processing**



Accelerate growth in **analog & sensors**



Expand in **power & energy** management



Accelerate growth with **industrial OEMs**

## Personal electronics



Lead in **selected** high-volume **smartphone** applications with differentiated products or custom solutions



Leverage **broad portfolio** to address high-volume applications

## Communications Equipment, Computers & Peripherals



Address **selected** high-volume **applications** with differentiated products or custom solutions



Address selected applications in **cellular** and **satellite communication** infrastructure



Leverage **broad portfolio** to address high-volume applications



# Microcontrollers & Digital ICs Group

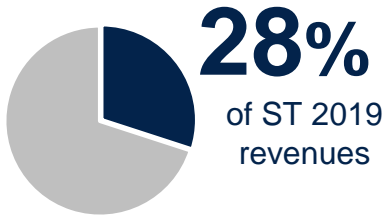
**Claude Dardanne**

President, Microcontrollers & Digital ICs Group



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# MDG group at a glance

## Key financial data by subgroup

### 2019 Revenue

**\$ 2.64B**

Microcontrollers & Digital ICs Group

**\$2.01B**

Microcontrollers,  
Memories and  
Secure MCUs  
**MMS**

**\$0.63B**

Radio Frequency  
Communication  
**RFC**

### CAGR 2016 - 2019

**+4.9%**

MDG

**+6.8%**





MMS

**-0.5%**

RFC\*

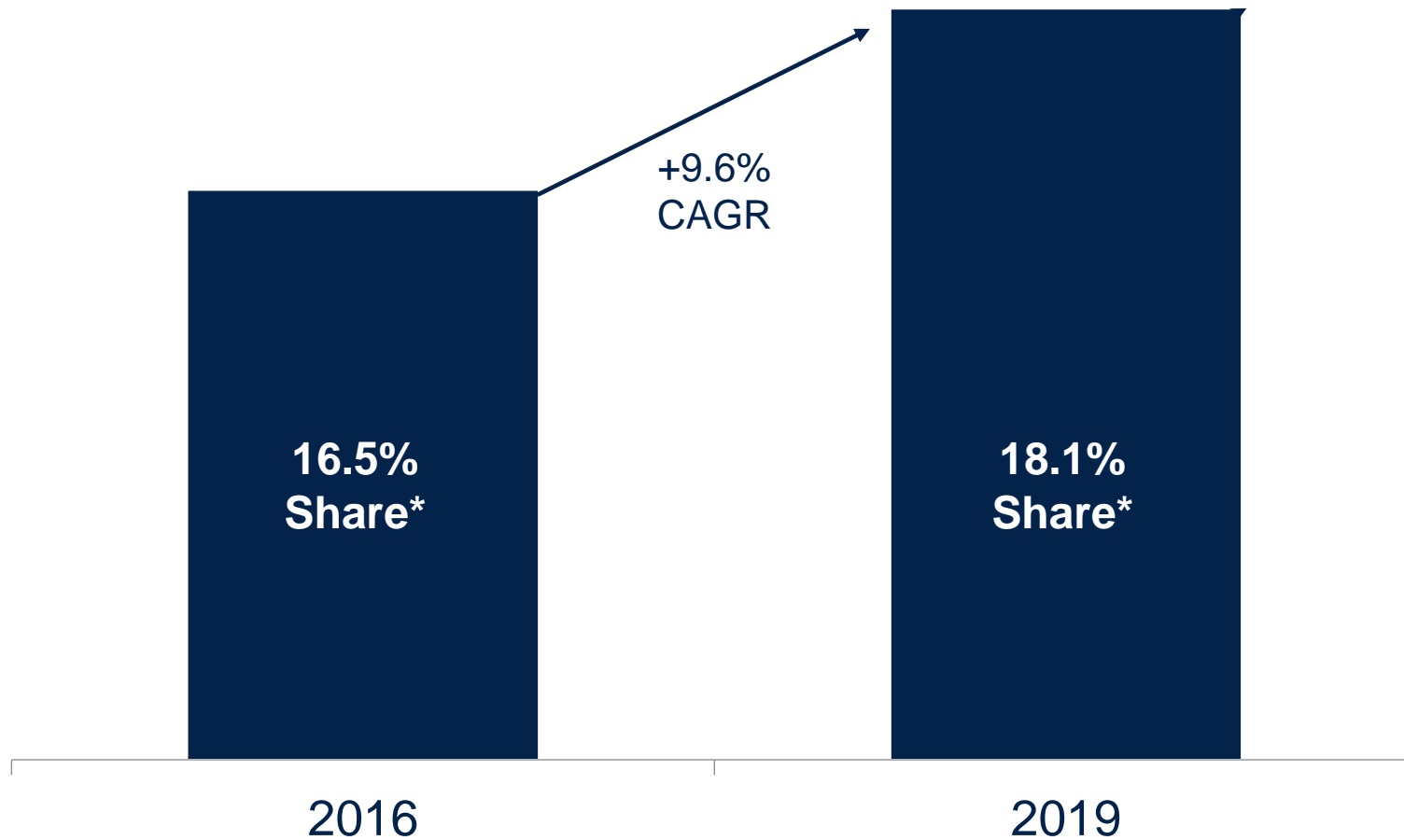
\* Including discontinued set-top  
box business

# Microcontrollers & Digital ICs Group












MMS		RFC		
Leadership in Embedded Processing		Leadership in Secure Solutions	Leadership in EEPROM	Focus in RF Communication
STM32 General Purpose Microcontroller	STM32 Industrial Microprocessor	Embedded Security Smartcards	ST25 RF EEPROM Serial Wired	ST Advanced RF Technologies
				<ul style="list-style-type: none"><li>• LEO satellite constellations</li><li>• 5G</li><li>• High speed communication infrastructure</li></ul>
#2	New	#3	#1	

# ST embedded processing position excl. automotive

ST Microcontrollers Revenues \*



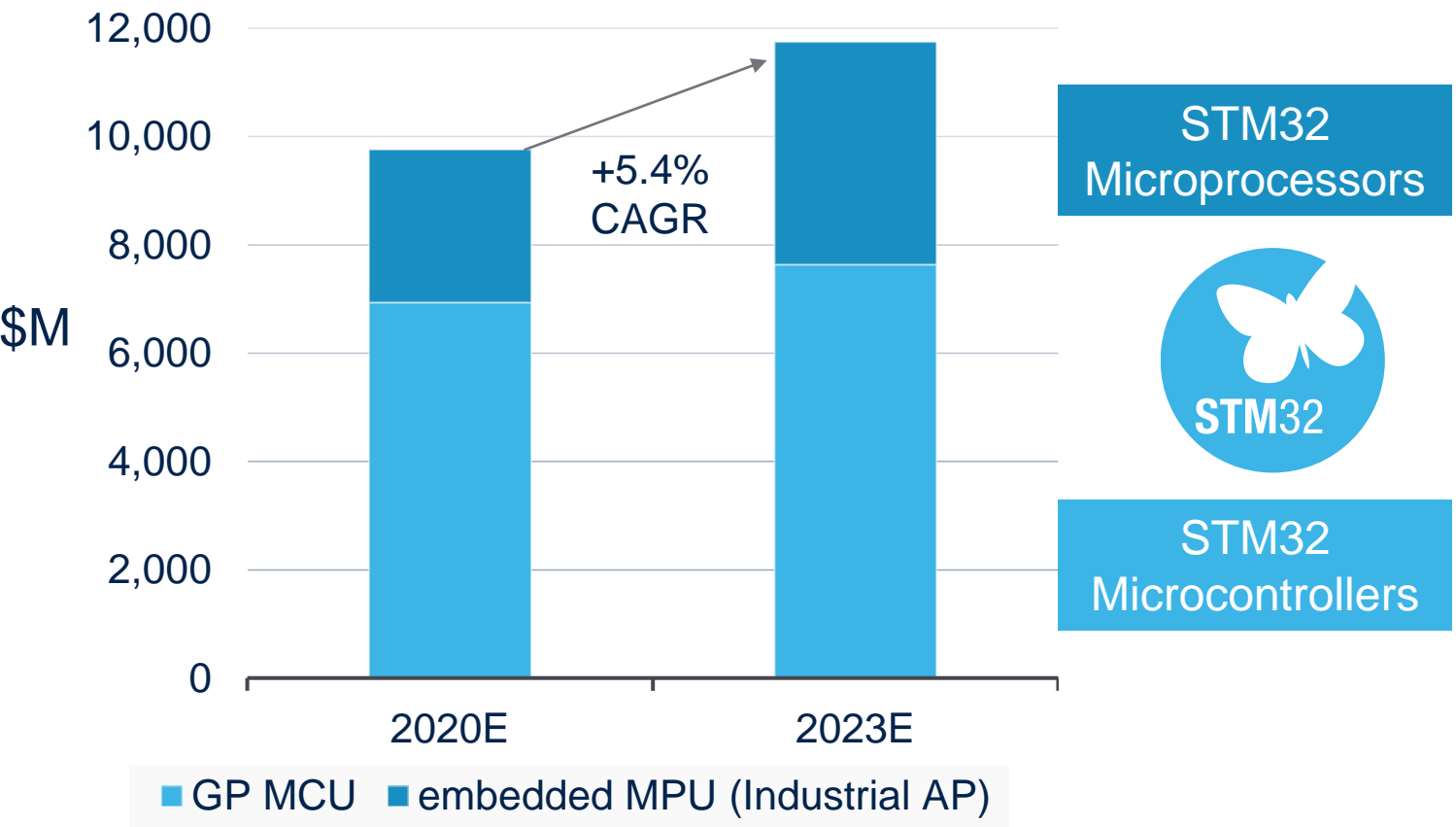
# General purpose microcontrollers\* ranking trend

Rank	2009	2010	2011	2012	2013	2014	2015	2016	2017	2018	2019
1	Renesas +	Renesas	Renesas	Renesas	Renesas	Renesas	Renesas	Microchip	Microchip	Microchip	Microchip
2	Panasonic	Atmel	Atmel	Atmel	Microchip	Microchip	Microchip +	Renesas	Renesas		
3	Microchip	Microchip	Microchip	Microchip	Atmel	Atmel				Renesas	Renesas
4	NEC	Samsung	TI	TI	TI		NXP	TI	TI	TI	TI
5	Toshiba	Toshiba	Toshiba			TI	Atmel	NXP	NXP	NXP	NXP +
6	Atmel	TI	Freescale	Fujitsu	Freescale	Freescale	TI	Cypress	Cypress	Infineon	Infineon +
7	Samsung	Freescale	Cypress	Freescale	Cypress	NXP +	Cypress	Infineon	Infineon	Cypress	Cypress
8	Freescale	Fujitsu	Fujitsu	Toshiba	Spansion	Spansion	Infineon	Silicon Lab	Silicon Lab	Toshiba	Nuvoton
9	TI	Panasonic		Cypress +	NXP	Cypress	Silicon Lab	Toshiba	Nuvoton	Silicon Labs	Toshiba
10	Fujitsu		Samsung	NXP	Toshiba	Infineon	Toshiba	Nuvoton	Toshiba	Nuvoton	Sil Lab
11		NXP	NXP	Samsung	Infineon	Toshiba	Nuvoton	Cobham	Cobham		Marvel

\* ST General Purpose MCU perimeter excluding automotive MCUs

\* General Purpose Microcontrollers = Omdia's Consumer MCU + Computers & Peripherals MCU + Wireless Communications MCU + Wired Communications MCU + General Purpose MCU

# Embedded processing market trend



- ### Key Applications
- Appliances & Smart Home
  - Wellness & fitness & Personal healthcare
  - Industrial & Power tools
  - Smart Metering
  - & Industry 4.0 / Factory Automation

# Embedded processing growth drivers - Industry 4.0

## Growth Drivers



Wireless Connectivity



End-to-end Security



AI at the Edge



Ultra Low Power



Motor control and Power system digitalization

## Industrial Example

Asset Tracking

Authentication

Predictive Maintenance

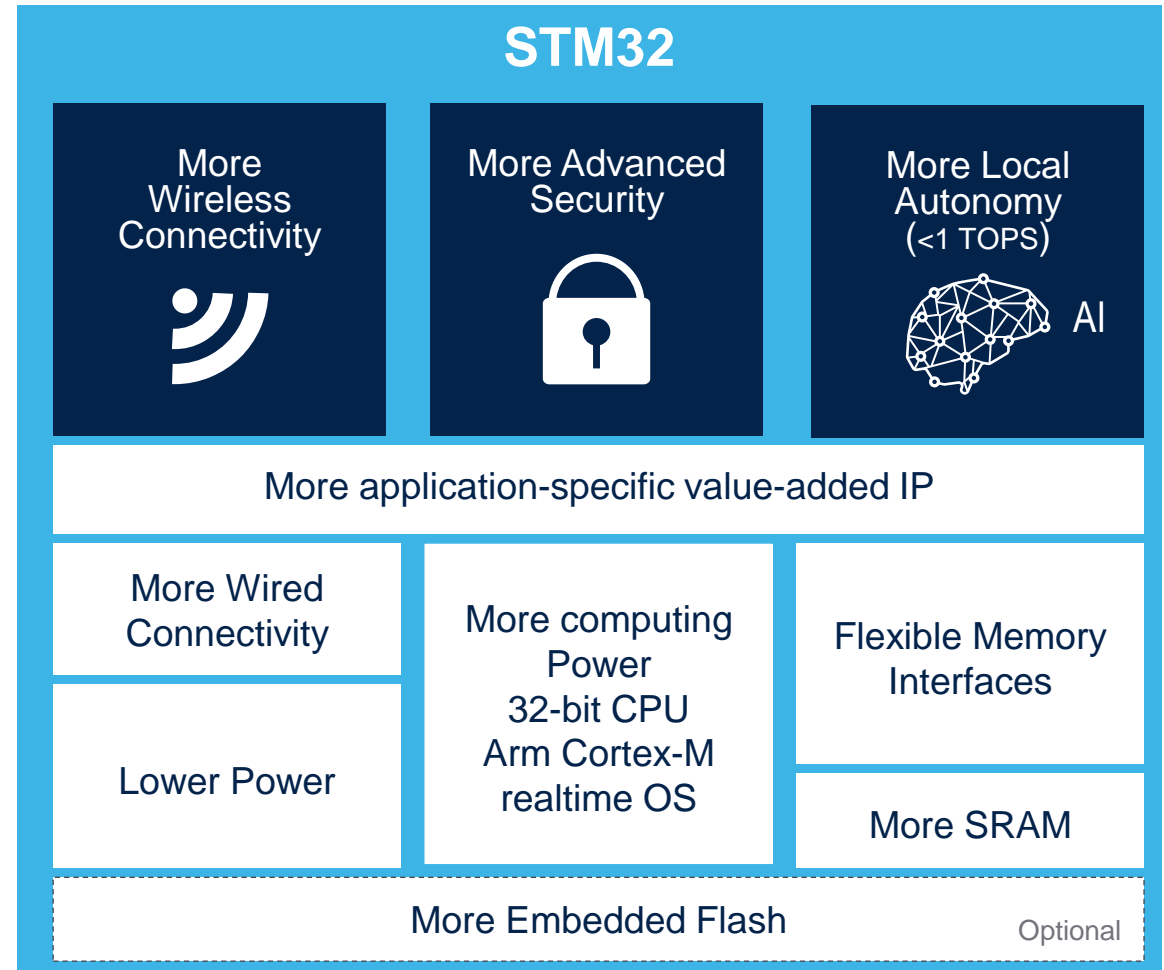
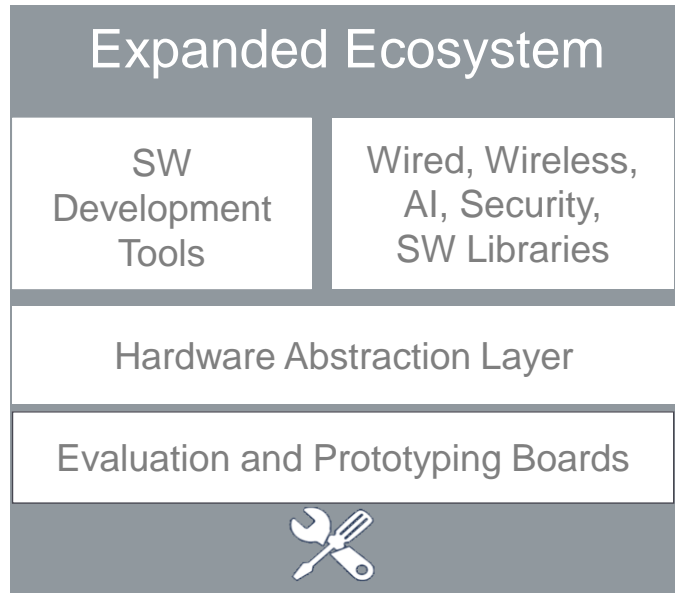
Asset Tracking

BLDC Motors



# STM32 product family

## Strengthening embedded processing
















Advanced Non-Volatile Memory technology : 18nm FD-SOI



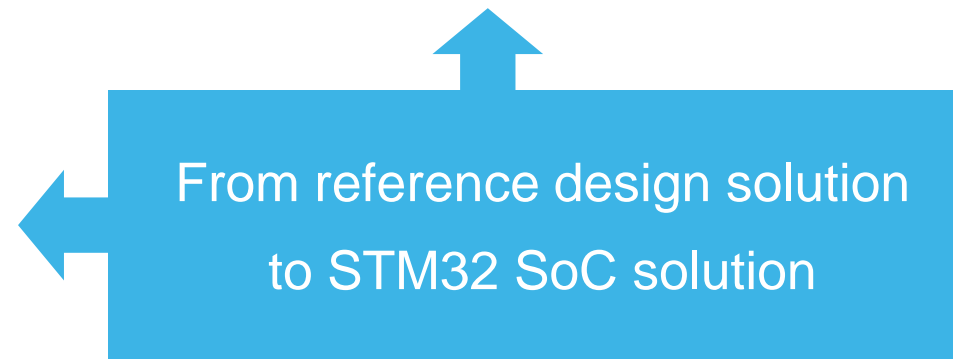
# STM32 wireless connectivity offer

## Network

BlueTooth			
ZigBee Thread	 		
Wi-Fi IoT			In Development
LoRa SigFox	 		
LTE Cat-M NB IoT	 		

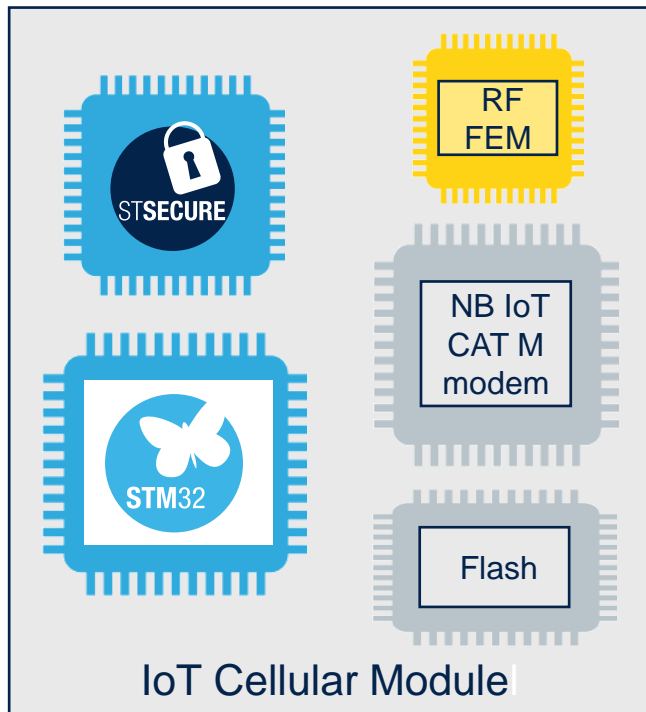
## Point-to-point

Near Field Communication			In Development
Ultra-Wide Band			

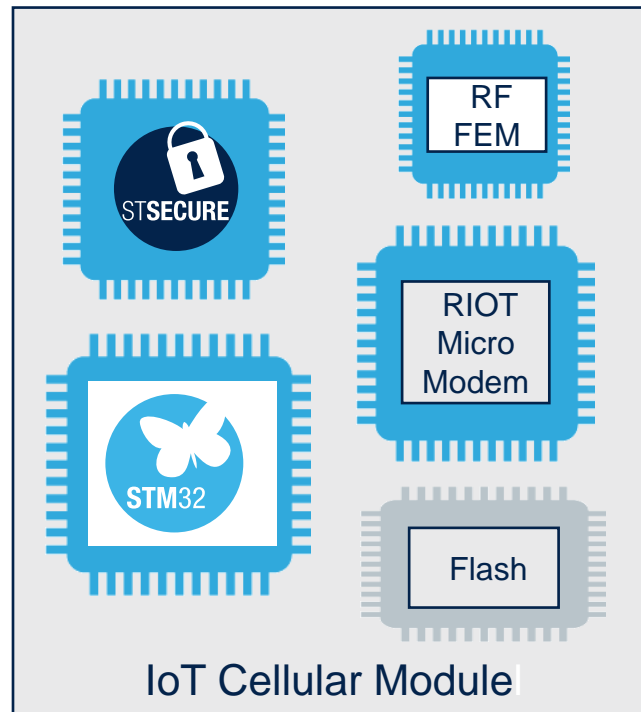


# IoT cellular connectivity Go to market strategy

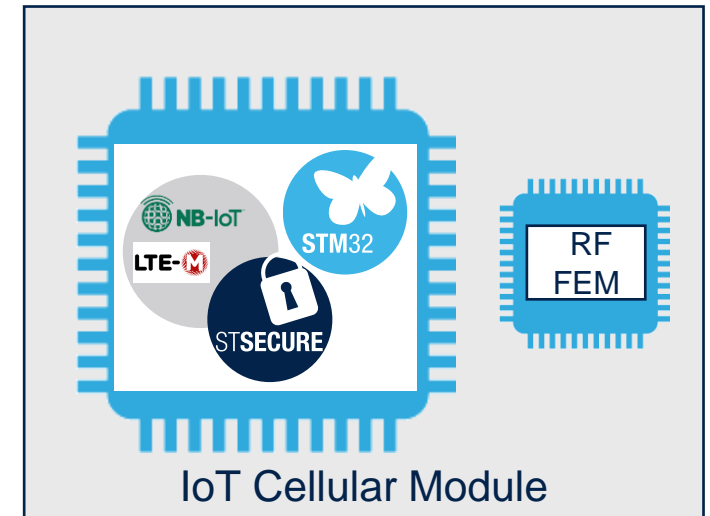
Turnkey cellular solution leveraging RF, ST SIM technology and the STM32 foundation



Certification managed by module maker or end customer

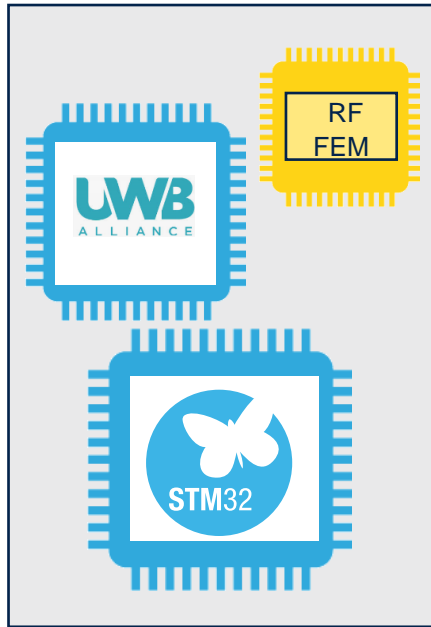


Low power turnkey solution  
Certification **managed by ST**

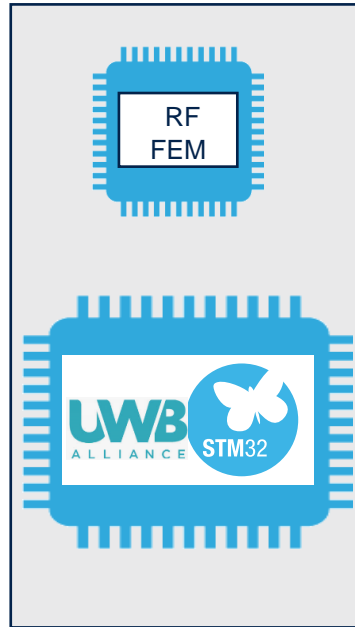


Fully integrated turnkey solution  
Certification **managed by ST**

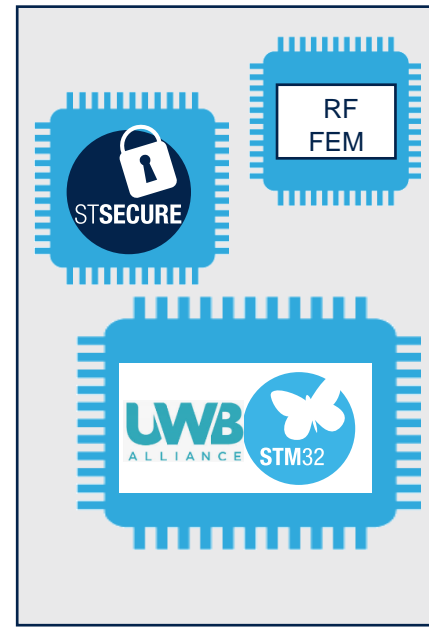
# Ultra Wide Band Go to market strategy



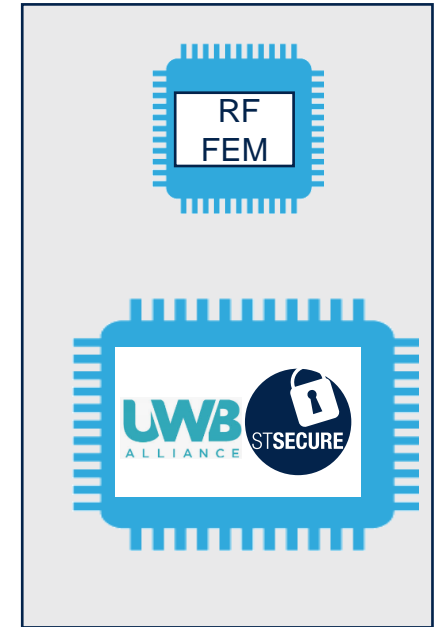
Industrial Module



Industrial chipset  
IoT Solution



Smartphone solution  
Automotive Secure solution

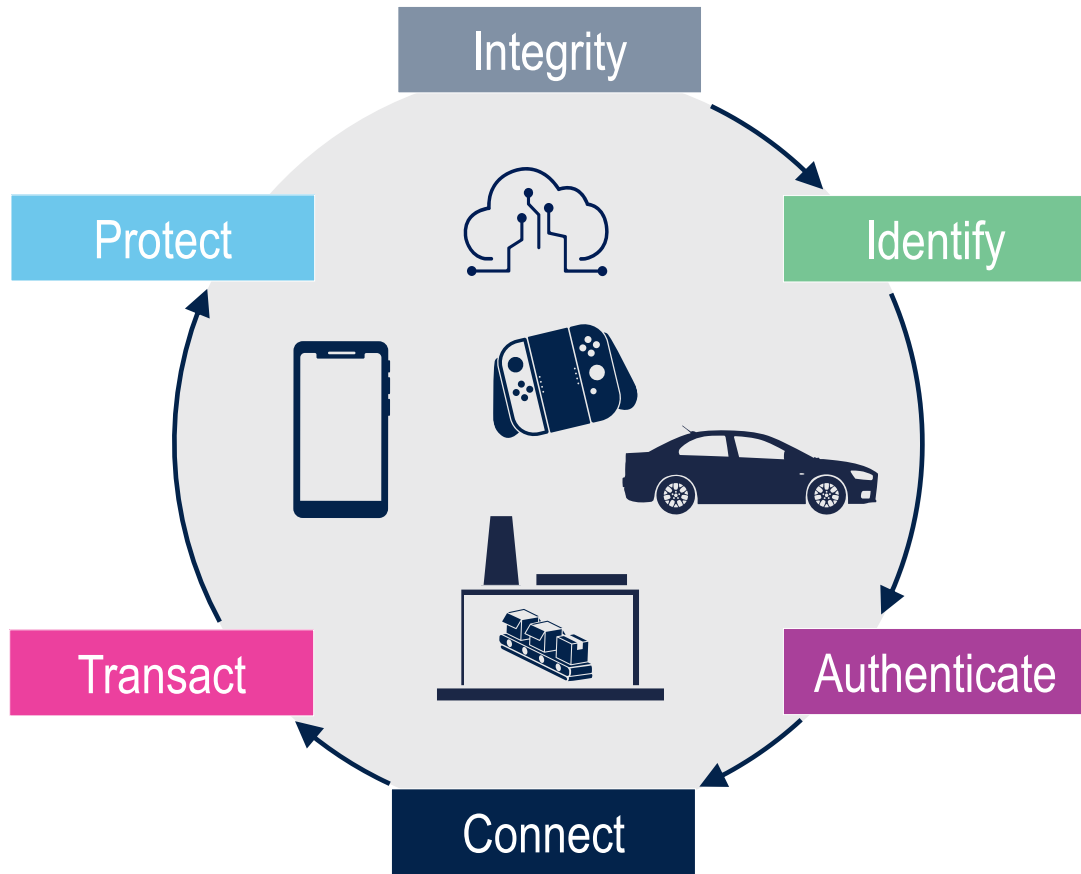


Smartphone chipset





# End-to-end security for embedded processing



Secure Boot	Abnormal Situation Handling	Silicon Device Lifecycle
Secure Install / Update	Crypto Engine	Software IP protection
Secure Storage	Audit/Log	Secure Manufacturing
Isolation	Identification, Authentication, Attestation	Application Lifecycle

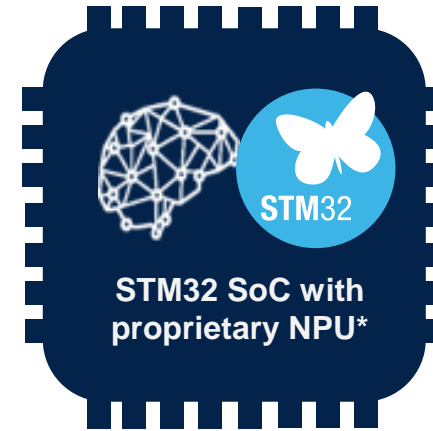
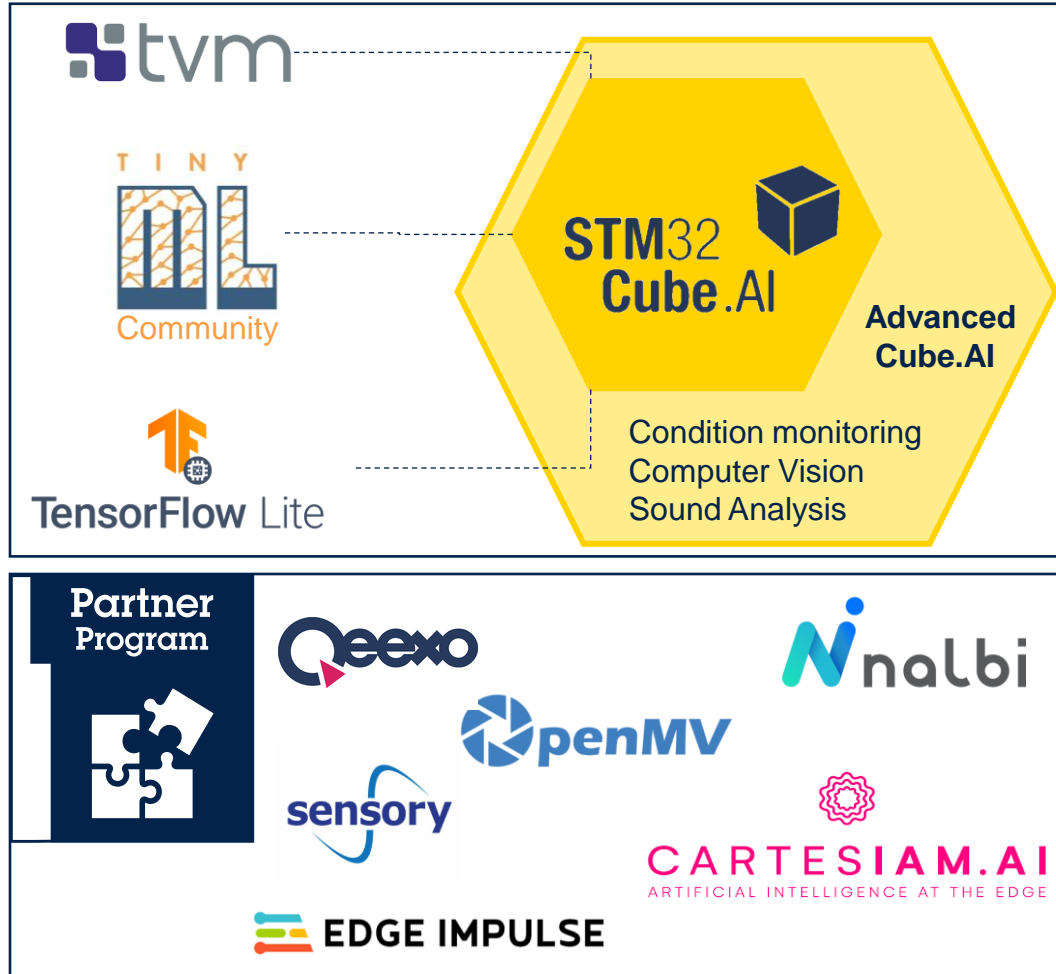


PSA = Platform Security Architecture, by ARM

SESIP = Security Evaluation Standard for IoT Platforms, by Global Platform



## STM32 enabling ever smarter objects



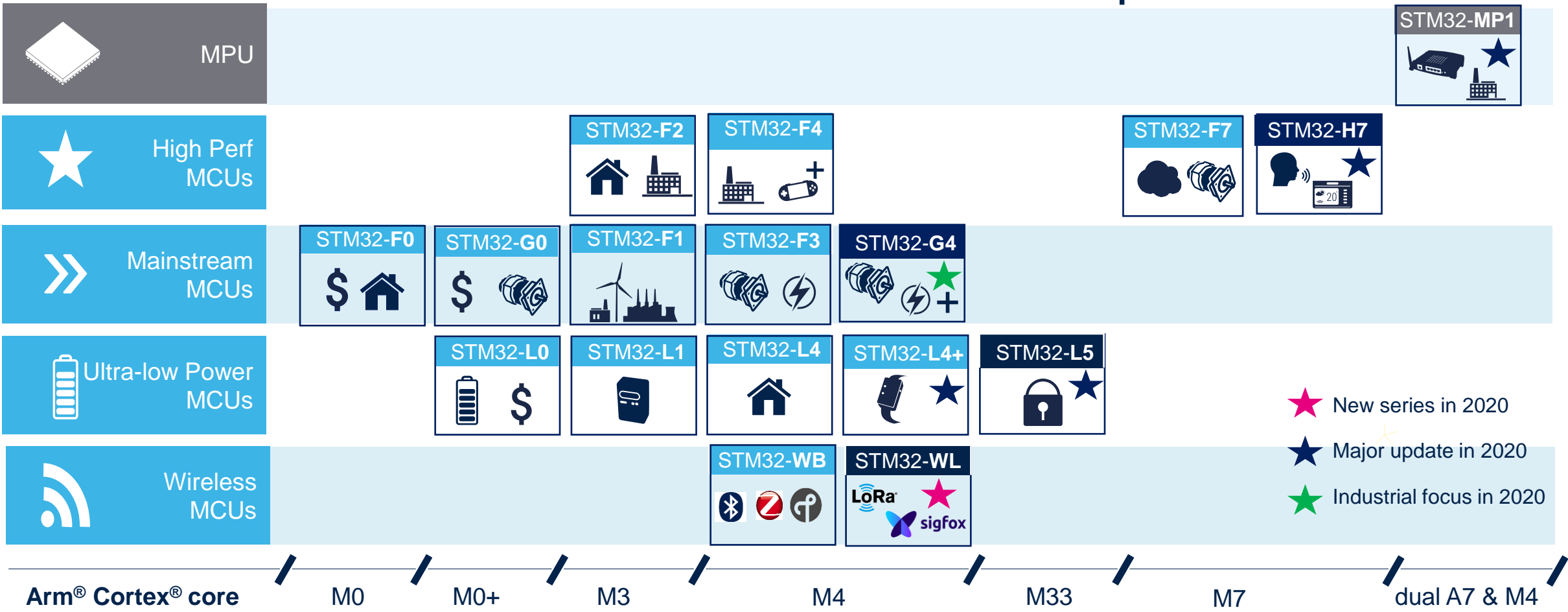
\* Neural Processing Unit





# Relentlessly growing portfolio Industrial & consumer markets focus

## Leader in Arm® Cortex®-M 32-bit General Purpose MCU



- ★ New series in 2020
- ★ Major update in 2020
- ★ Industrial focus in 2020

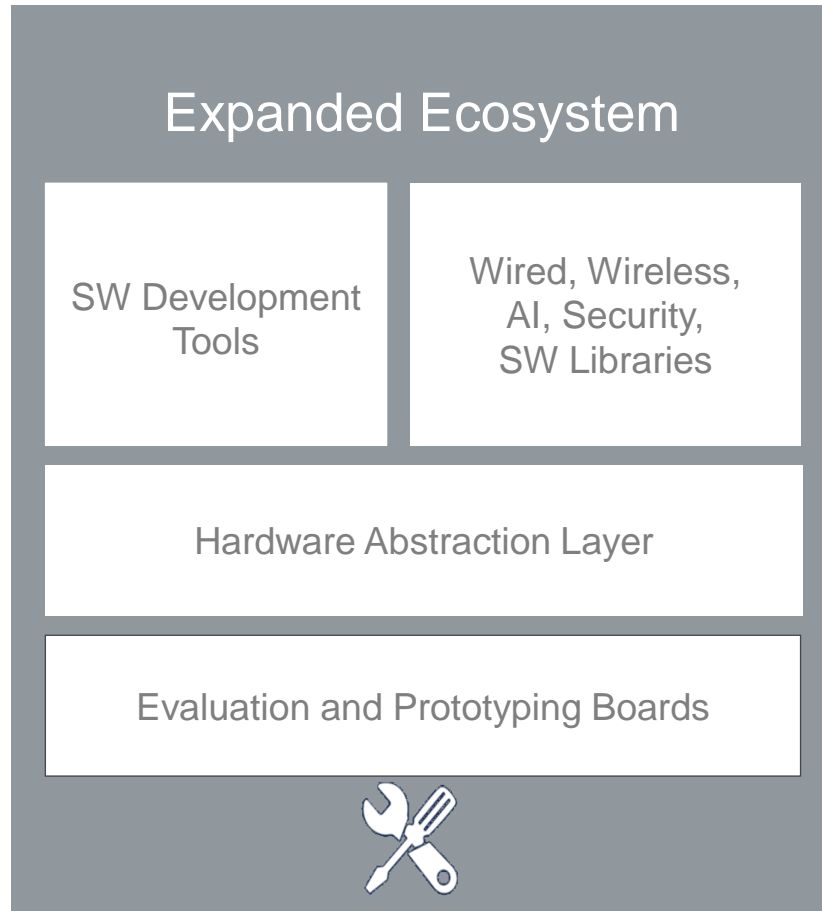
Over **6 Billion** STM32 shipped



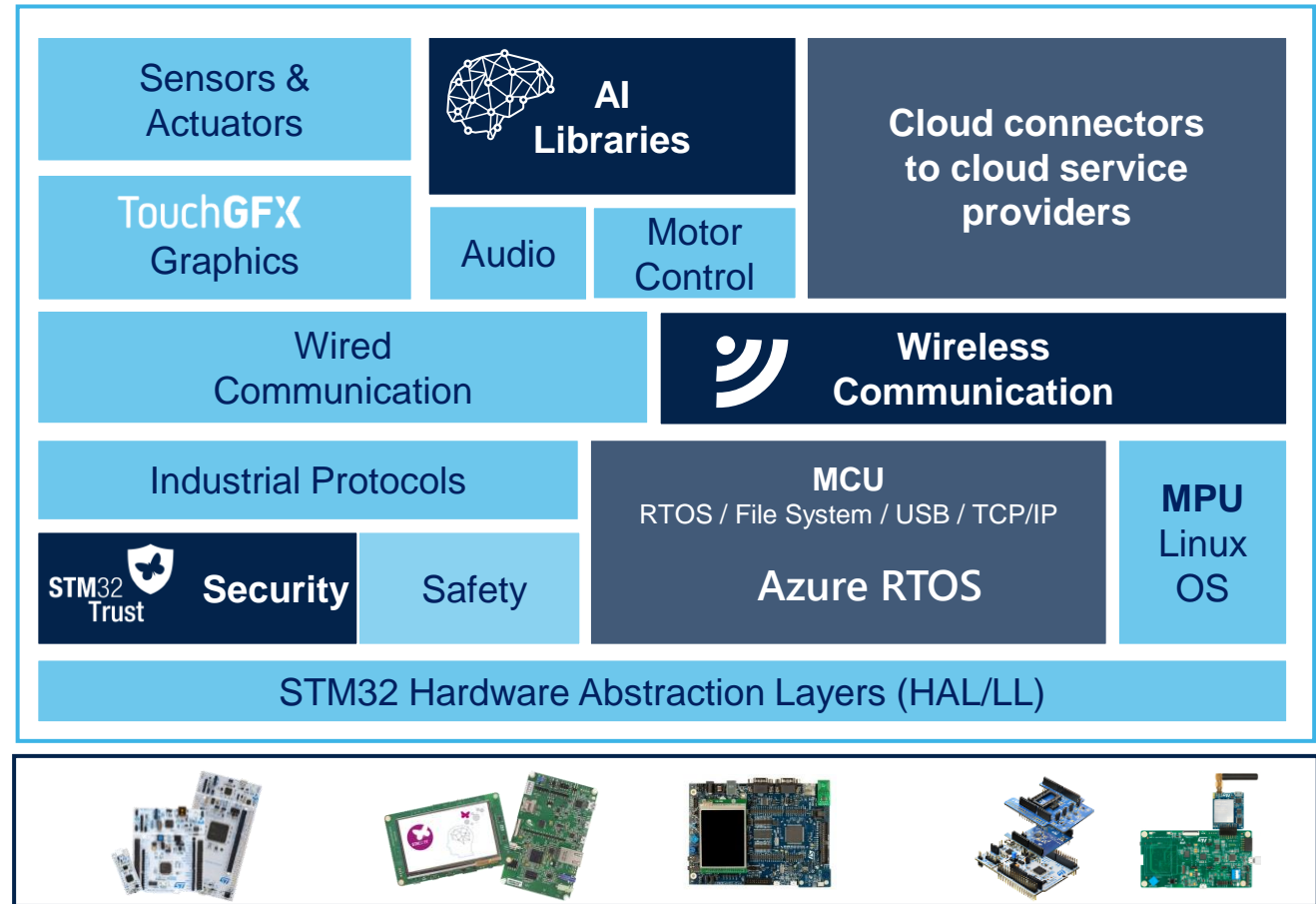


# State-of-the-Art STM32 ecosystem

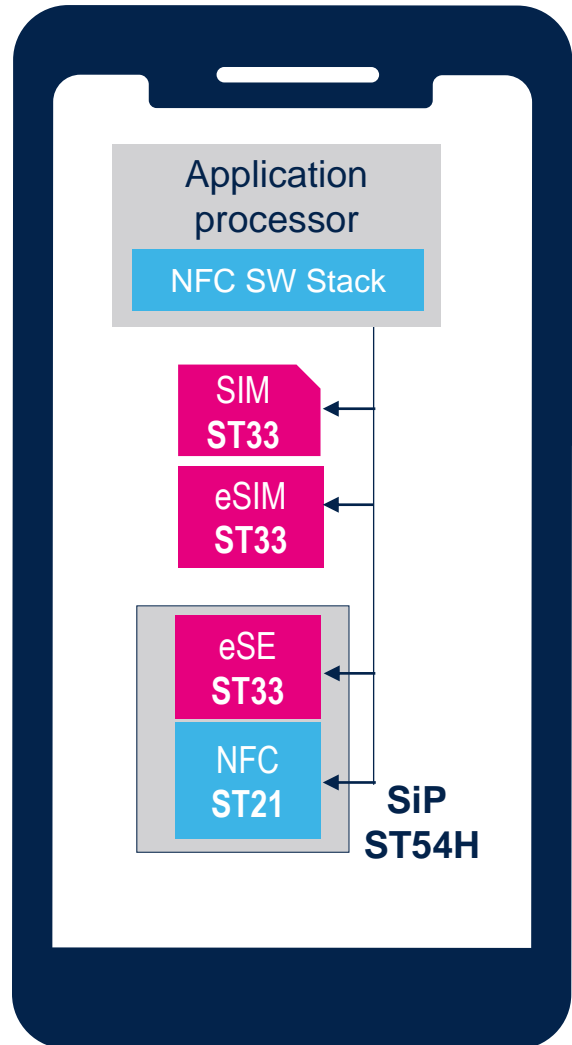
## Key for OEMs to chose an MCU/MPU



### User Application



# Secure solutions for personal electronics



## Network Authentication

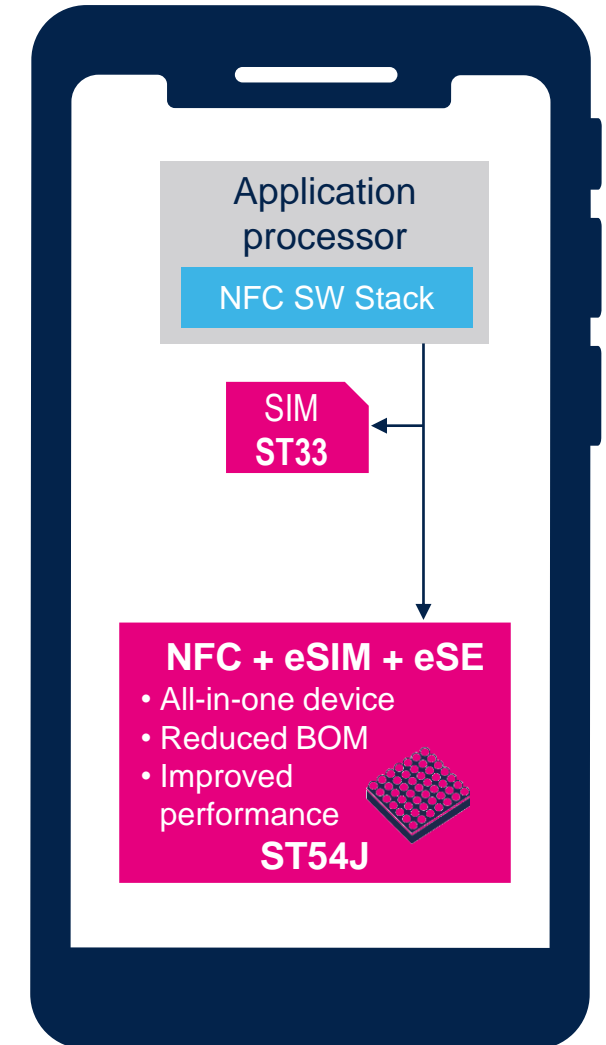
Basic SIM

eSIM → #1 WW Supplier

## Mobile transaction

- Secure element
- NFC controller (\*)

(\*) Power efficiency & dynamic antenna tuning  
ST patented technologies





# Secure solutions Automotive market

## Secure Connectivity for safety & maintenance



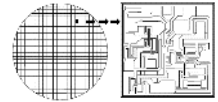
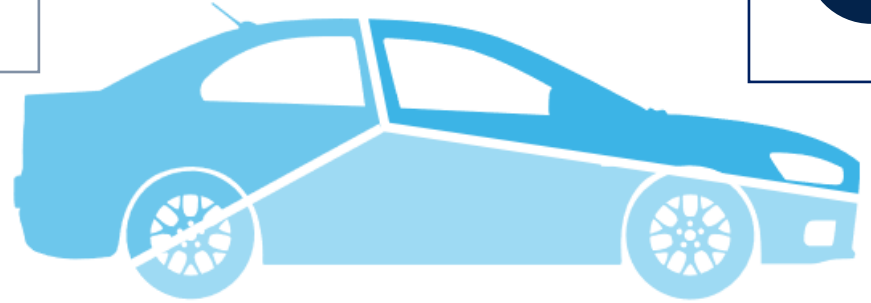
eCall (\*)  
Telematics  
**ST4SIM-A**  
eSIM for automotive

(\*) Mandatory emergency  
Call feature

## Device Integrity for Engine Control



Tamper resistant device  
SW Integrity checks  
Secure storage of confidential data  
**ST33-A Secure element**



AEC-Q100

## Authentication for door lock-access : CCC V2

### NFC Digital key

Door handle & center console



**ST25R3920** NFC reader



**ST33-A** Secure element



### NFC Secure car access

Connected Car Consortium compliant

**ST54** Secure Element, NFC Controller



**ST31** Secure element, NFC card emulation

## Authentication for door lock access : CCC V3



**STM32WU** UWB Controller

**STM32WB** BLE Controller



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# Contactless Market : Booming opportunities ST25 NFC tags & readers pervasion

Comprehensive portfolio :  
Short range – Long range

Growing contactless markets :  
Personal electronics, Automotive, Industrial, Healthcare  
> 10% CAGR 2018-2023

Complete  
ecosystem  
to ease  
adoption

Readers  
ST25R



Tags  
ST25T



Dynamic tags  
ST25D



Best-in-class RF performance



- Lighting
- Metering
- Payment
- Transportation
- Consumer electronics
- Consumer brands
- Automotive
- Healthcare

Active member

CARCONNECTIVITY  
consortium®



# Wireless communication trends

## More bandwidth everywhere

### User expectations

- Improved global coverage from dense areas to rural areas
  - Very high data rate  
**> 1 Gbps**
  - Reduced latency  
**< 1 ms**
- 
- High density of connected nodes  
**> 10<sup>6</sup> / km<sup>2</sup>**



- Disruptive innovation
- mmWave frequency
- Massive beamforming & MIMO
- Data Rate > 10Gbps

- 4G continuity
- Data rate >1 Gbps
- Latency <1 ms
- Improve mobility/security

- Massive IoT market



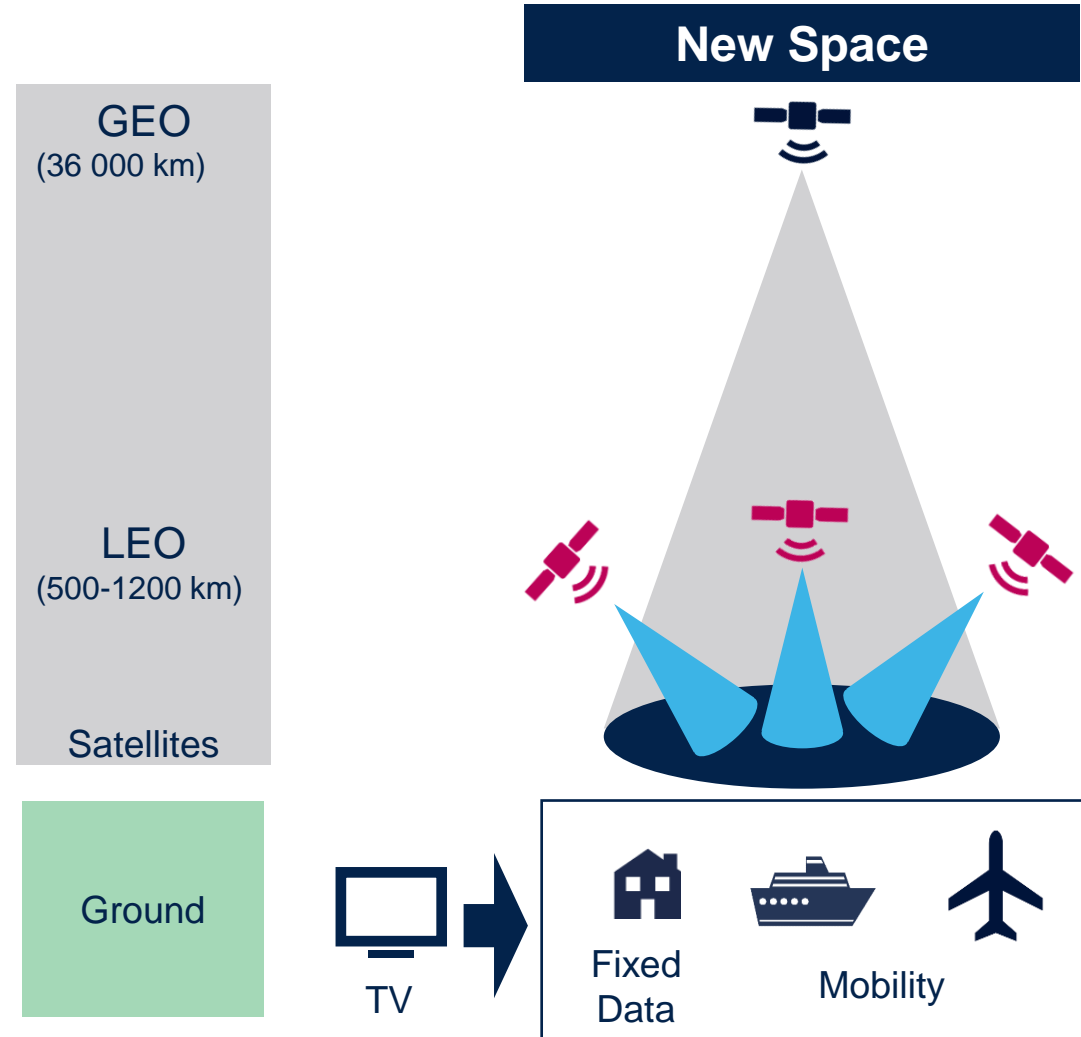
### LEO satellite constellations

**> 12 GHz**



- Disruptive innovation
- mmWave frequency
- Massive beamforming & MIMO
- Data Rate > 1 Gbps

# LEO satellite constellations



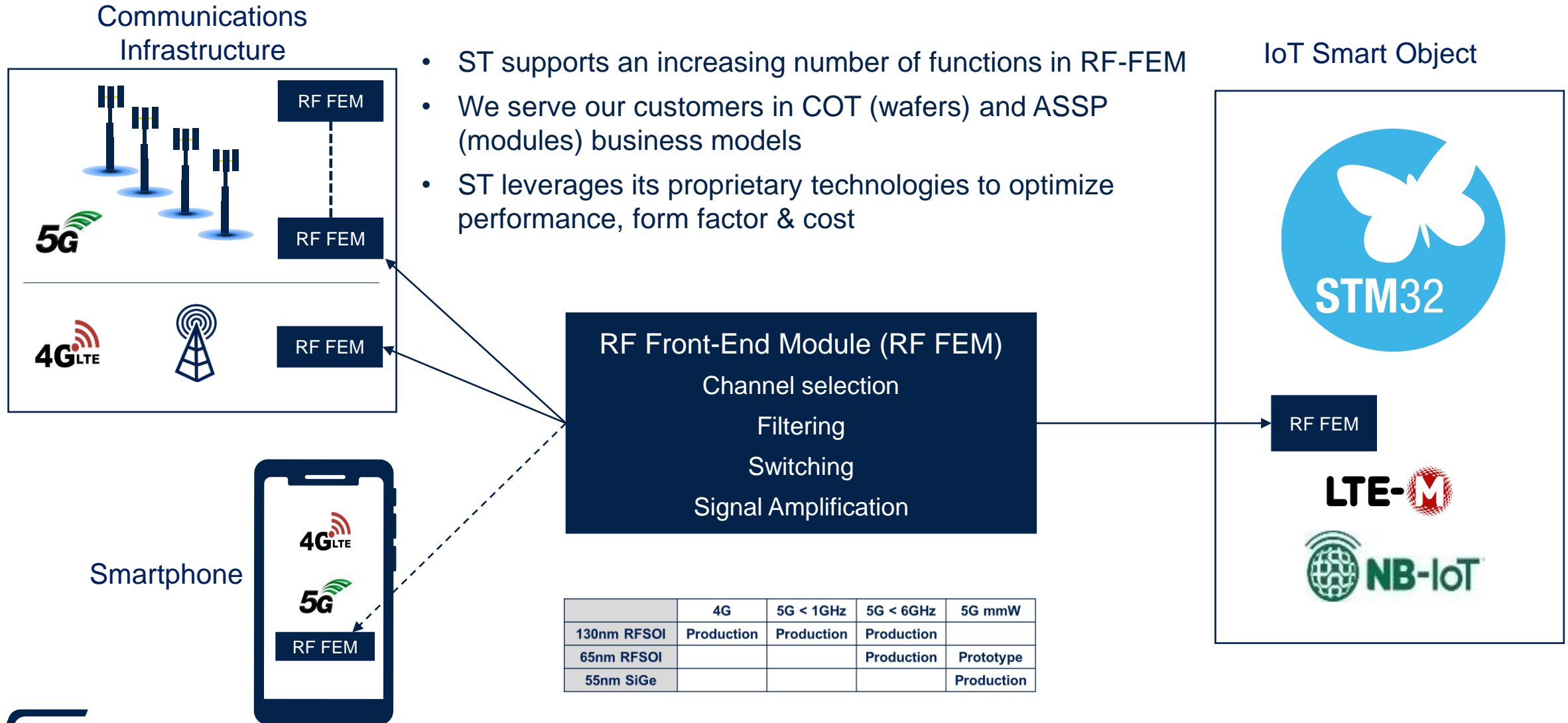
## ST knowhow

- Proprietary advanced Radio Frequency Silicon technologies : 130nm SiGe & 28nm FD-SOI
- Phased Array antenna design (Beam forming)

## ST activities

- Enabling low-power, high-bandwidth integrated solutions for the booming LEO SAT constellation market including satellite & associated user terminals
- Volume production in 2020

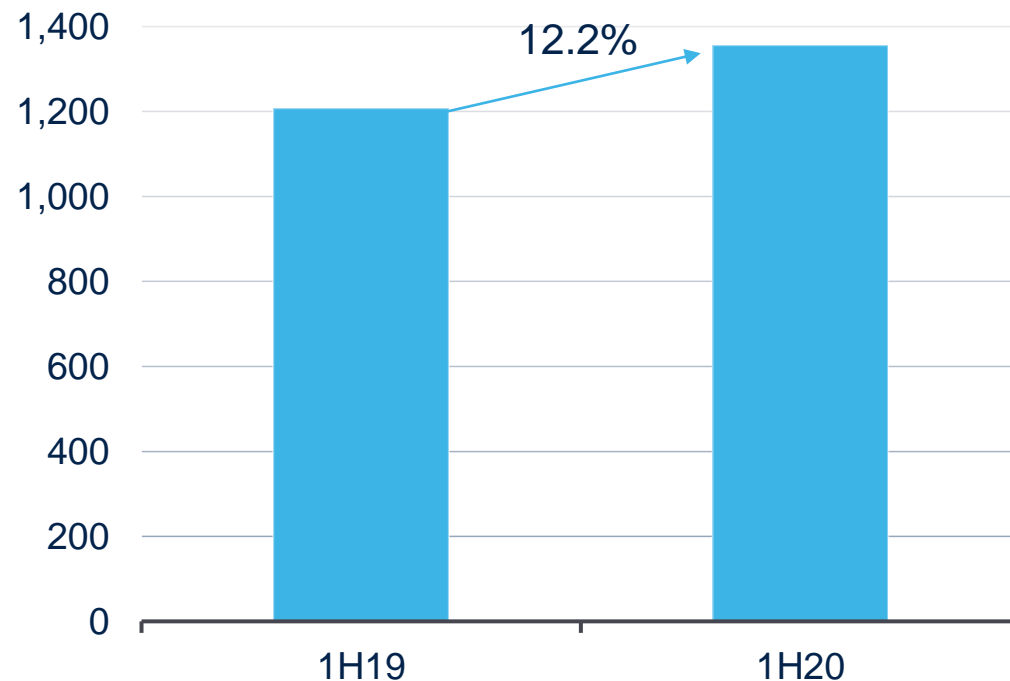
# Technologies for Front-End Modules



- ST supports an increasing number of functions in RF-FEM
- We serve our customers in COT (wafers) and ASSP (modules) business models
- ST leverages its proprietary technologies to optimize performance, form factor & cost

# Takeaways

MDG revenue trend (\$M)



- Reinforce our Embedded Processing leadership position
- Consolidate Leadership position for Secure solutions
- Directly address RF communication infrastructure and IoT, capitalizing on proprietary technologies

# Thank you

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